

## PMP11140 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
I PCB	1		PMP11140	Any	Printed Circuit Board	
3.3Aux, Bode1, DrvSig, Vin, Vout	5	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
Bode2, PowerGood	2	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
BodeGND, DrvSigRtn, VinRtn, VoutRtn	4	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
C1	1	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
C2	1	10uF	GRM31CR71E106KA12L	MuRata	CAP, CERM, 10 µF, 25 V, +/- 10%, X7R, 1206	1206
C3, C6	2	0.1uF	GRM155R61E104KA87D	MuRata	CAP, CERM, 0.1uF, 25V, +/-10%, X5R, 0402	0402
C4	1	10pF	GRM1555C1H100JA01D	MuRata	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C5	1	1500pF	GRM155R71H152KA01D	MuRata	CAP, CERM, 1500 pF, 50 V, +/- 10%, X7R, 0402	0402
C7	1	0.1uF	GCM155R71C104KA55D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X7R, 0402	0402
C8, C16	2	330pF	GRM1555C1H331JA01D	MuRata	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0402	0402
C9, C10, C11, C12	4	100uF	GRM31CR60G107ME39L	MuRata	CAP, CERM, 100 µF, 4 V, +/- 20%, X5R, 1206	1206
C13	1	1500pF	GRM155R71H152KA01D	MuRata	CAP, CERM, 1500pF, 50V, +/-10%, X7R, 0402	0402
C14	1	220pF	GRM155R71H221KA01D	MuRata	CAP, CERM, 220 pF, 50 V, +/- 10%, X7R, 0402	0402
C15, C17, C231	3	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1uF, 10V, +/-10%, X5R, 0402	0402
C103, C191	2	22uF	C3225X5R1C226M	TDK	CAP, CERM, 22 µF, 16 V, +/- 20%, X5R, 1210	1210
C104	0	DNP	C1210C107M9PACTU	Kemet	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210
C105	0	DNP	EEFSX0E471ER	Panasonic	CAP, Polymer, 470 µF, 2.5 V, +/- 20%, 9 ohm, 7.3x1.8x4.3mm SMD	7.3x1.8x4.3mm
C111	1	0.1uF	GRM155R61E104KA87D	MuRata	CAP, CERM, 0.1 µF, 25 V, +/- 10%, X5R, 0402	0402
C192	1	100uF	UBT1E101MPD1TD	Nichicon	CAP, AL, 100 µF, 25 V, +/- 20%, 0.13 ohm, TH	Cap D8.0x11.5mm
C201, C207, C208, C209	4	0.1uF	C1005X7R1H104M	TDK	CAP, CERM, 0.1uF, 50V, +/-20%, X7R, 0402	0402
C300	1	0.1uF	C0805C104K1RACTU	Kemet	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0805	0805
C330	1	4.7uF	C2012X5R0J475M	TDK	CAP, CERM, 4.7uF, 6.3V, +/-20%, X5R, 0805	0805
CNTL, Sense-	2	Yellow	5004	Keystone	Test Point, Miniature, Yellow, TH	Yellow Miniature Testpoint
Communications	1		5103308-1	TE Connectivity	Header (shrouded), 100mil, 5x2, Gold, TH	5x2 Shrouded header
D203	1	30V	BAT54WS-7-F	Diodes Inc.	Diode, Schottky, 30V, 0.2A, SOD-323	SOD-323
D240, D241	2	30V	MBR0530T1G	ON Semiconductor	Diode, Schottky, 30V, 0.5A, SOD-123	SOD-123
D242	1	Red	LTST-C170KRKT	Lite-On	LED, Red, SMD	LED_0805
DynEN	1		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil, Tin
H9, H10, H11, H12	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J100, J190	2		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
J111	1		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX SMD
L1	1	3.3uH	IHLP2020CZER3R3M11	Vishay-Dale	Inductor, Shielded Drum Core, Powdered Iron, 3.3 µH, 5.5 A, 0.0404 ohm, SMD	5.18x3x5.5mm
OFF_ON	1		PEC03SAAN	Sullins Connector Solutions	Header, 100mil, 3x1, Tin, TH	Header, 3 PIN, 100mil, Tin
Q1	1	20V	CSD85301Q2	Texas Instruments	MOSFET, N-CH, 20 V, 6.7 A,	

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Q250	1	30V	CSD17313Q2	Texas Instruments	MOSFET, N-CH, 30 V, 5 A, SON 2x2mm	SON 2x2mm
R1	1	10	CRCW040210R0JNED	Vishay-Dale	RES, 10 ohm, 5%, 0.063W, 0402	0402
R2	1	1.50k	CRCW04021K50FKED	Vishay-Dale	RES, 1.50 k, 1%, 0.063 W, 0402	0402
R3, R5	2	36.5k	CRCW040236K5FKED	Vishay-Dale	RES, 36.5k ohm, 1%, 0.063W, 0402	0402
R4, R8, R207, R241, R242, R301, R302, R303, R304	9	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0k ohm, 1%, 0.063W, 0402	0402
R6	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R7, R16	2	0	CRCW04020000Z0ED	Vishay-Dale	RES, 0 ohm, 5%, 0.063W, 0402	0402
R9	1	2.49k	CRCW04022K49FKED	Vishay-Dale	RES, 2.49 k, 1%, 0.063 W, 0402	0402
R10	1	6.8	CRCW04026R80JNED	Vishay-Dale	RES, 6.8, 5%, 0.063 W, 0402	0402
R11	1	249	CRCW0402249RFKED	Vishay-Dale	RES, 249, 1%, 0.063 W, 0402	0402
R12, R14	2	100	CRCW0402100RFKED	Vishay-Dale	RES, 100 ohm, 1%, 0.063W, 0402	0402
R13	1	4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99 k, 1%, 0.063 W, 0402	0402
R15, R100, R103	3	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9 ohm, 1%, 0.063W, 0402	0402
R111	1	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R192	1	1.0	CRCW06031R00JNEA	Vishay-Dale	RES, 1.0, 5%, 0.1 W, 0603	0603
R206	1	8.06k	CRCW04028K06FKED	Vishay-Dale	RES, 8.06k ohm, 1%, 0.063W, 0402	0402
R208	1	200k	CRCW0402200KFKED	Vishay-Dale	RES, 200k ohm, 1%, 0.063W, 0402	0402
R243	1	330	CRCW0402330RJNED	Vishay-Dale	RES, 330 ohm, 5%, 0.063W, 0402	0402
R251, R252	2	0.47	CSRN2512FKR470	Stackpole Electronics Inc	RES, 0.47, 1%, 2 W, 2512	2512
Sense+	1	Orange	5003	Keystone	Test Point, Miniature, Orange, TH	Orange Miniature Testpoint
TP105, TP193	2	SMT	5016	Keystone	Test Point, Compact, SMT	Testpoint_Keystone_ Compact
TP199	1	SMT	5015	Keystone	Test Point, Miniature, SMT	Testpoint_Keystone_ Miniature
U1	1		TPS40400RHL	Texas Instruments	3.0-V TO 20-V PMBus SYNCHRONOUS BUCK CONTROLLER, RHL0024A	RHL0024A
U201	1		TLC555CD	Texas Instruments	LinCMOS Timer, D0008A	D0008A
U230	1		UCC27324D	Texas Instruments	DUAL 4-A PEAK HIGH SPEED LOW- SIDE POWER MOSFET DRIVERS, D0008A	D0008A
U330	1		TPS70933DRV	Texas Instruments	150-mA, 3.3-V, 1-µA IQ Voltage Regulators with Enable, DRV0006A	DRV0006A
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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